

**AMENDMENTS TO THE ABSTRACT**

Please replace the paragraph beginning at page 32, line 2, with the following rewritten paragraph:

**ABSTRACT**

-- ~~Disclosed is a~~ A plating-pretreatment solution comprising an organic sulfonic acid, thiourea, fluoroboric acid and hypophosphorous acid. ~~Also disclosed is~~ and a plating-pretreatment method comprising contacting a film carrier tape in which a wiring pattern is formed on a surface of an insulating film with a plating-pretreatment solution comprising an organic sulfonic acid, thiourea, fluoroboric acid and hypophosphorous acid to remove metals remaining on the insulating film. According to the plating-pretreatment solution and the plating-pretreatment method, metals remaining on the surface of the insulating film exposed by etching ~~can be~~ are removed, and ~~the~~ the occurrence of migration ~~can be~~ is prevented. --